



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	MD CHAMPION NAME	Representative Title	Group MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M95020-WMN6TP	PH07*95021KA	B	3068	2016-04-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	80.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	-	8	L bend	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	PHO7*95021KA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.509	mg	supplier	die	Silicon (Si)	7440-21-3		0.490	mg	962672	6125
Die or Dies (choose)				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	3929	25
Die or Dies (choose)				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	1965	13
Die or Dies (choose)				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	31434	200
Lead-frame	Other inorganic materials	17.694	mg	supplier	alloy	Copper (Cu)	7440-50-8		17.243	mg	974500	215533
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.415	mg	23460	5189
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.021	mg	1200	265
Lead-frame				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.015	mg	840	186
Lead-frame Coating	Other inorganic materials	0.078	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.071	mg	914840	890
Lead-frame Coating				supplier	coating	Palladium (Pd)	7440-05-3		0.002	mg	29660	29
Lead-frame Coating				supplier	coating	Gold (Au)	7440-57-5		0.002	mg	27750	27
Lead-frame Coating				supplier	coating	Silver (Ag)	7440-22-4		0.002	mg	27750	27
Die Attach	Other inorganic materials	0.578	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.520	mg	900000	6502
Die Attach				supplier	glue or soft solder	acrylate	proprietary		0.035	mg	60000	433
Die Attach				supplier	glue or soft solder	Methacrylate	proprietary		0.022	mg	38000	275
Die Attach				supplier	glue or soft solder	acrylate	proprietary		0.001	mg	2000	14
Wires	Other inorganic materials	0.029	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.029	mg	1000000	365
Encapsulation	Other inorganic materials	61.111	mg	supplier	Moulding Compound	Epoxy Resin	proprietary		4.585	mg	75023	57309
Encapsulation				supplier	Moulding Compound	Phenol Resin	proprietary		3.056	mg	50015	38206
Encapsulation				supplier	Moulding Compound	Silica, vitreous	60676-86-0		52.920	mg	865959	661499
Encapsulation				supplier	Moulding Compound	Carbon-black	1333-86-4		0.306	mg	5002	3821
Encapsulation				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.245	mg	4001	3056
Finishing	Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	914840	9
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	29660	0
Finishing				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	27750	0
Finishing				supplier	connections coating	Silver (Ag)	7440-22-4		0.000	mg	27750	0